

Alutin 51L

Low Temperature, Self-Fluxing, Tin-Silver Soldering Paste

DESCRIPTION

AluTin 51 is supplied as a viscous gel flux. It is designed for the soldering of aluminium and the joining of aluminium with copper, brass or copper-aluminium.

Application: This flux is basically used with the following alloys:

CASTOLIN 1827 and Alutin 51

Aluminium joining: (Si + Mg < up to 2%), or for the dissimilar joining of copper/aluminium

PROCEDURE FOR USE

Preparation :

If necessary, clean the joint surfaces and round off any sharp edges.

- Degrease the parts with an appropriate solvent.
- Coat all the joint parts with AluTin 51 flux.
- Place the parts in their definitive position.
- Adjust the welding torch to obtain a gentle, slightly carburising flame.
- Indirectly and uniformly heat the parts to be joined, up to the bonding temperature.
- Do not overheat the flux, in order to prevent deterioration and do not apply the flame directly onto the flux.
- Apply the end of the filler alloy rod to the joint. The alloy filler metal spreads to the hottest areas of the surfaces to be joined.
- Melt the filler metal until the joint has been completely filled.

Instructions for Use:

The AluTin 51 Flux residues are water soluble. They are generally removed by washing in hot water.

***NOTE: AluTin 51 is available in Rod form**

TECHNICAL DATA:

Tensile Strength: 105 N/mm² (15,000 psi)

Shear Strength: 68 N/mm² (10,000 psi)

Electrical Conductivity - IACS: 16.5%

Thermal Expansion Coef.: 12 x 10⁻⁶ in / F
(20 - 212°F)

Solidus Temperature1: 430°F (220°C)

Liquidus Temperature2: 430°F (220°C)

Maximum Brazing Temp.: 450°F (230°C)

DIAMETER
2.5mm
3.15mm